



Sheet 1 of 1

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U.S. Department of Commerce
Patent and Trademark Office

Attorney's Docket No.
05542-516001

Application No.
10/721,769

Information Disclosure Statement
by Applicant

(Use several sheets if necessary)

(37 CFR §1.98(b))

Applicant
Birang et al.

Filing Date
November 24, 2003

Group Art Unit
2812

U.S. Patent Documents

Examiner Initial	Desig. ID	Document Number	Publication Date	Patentee	Class	Subclass	Filing Date If Appropriate
AA	5,081,796	01/1992	Schultz	—	—	—	—
AB	5,486,129	01/1996	Sandhu et al.	—	—	—	—
AC	5,658,183	08/1997	Sandhu et al.	—	—	—	—
AD	5,722,875	05/1998	Iwashita et al.	—	—	—	—
AE	5,730,642	03/1998	Sandhu et al.	—	—	—	—
AF	5,741,070	04/1998	Moslehi	—	—	—	—
AG	5,773,316	06/1998	Kurosaki et al.	—	—	—	—
AH	5,840,614	11/1998	Sim et al.	—	—	—	—
AI	5,985,094	11/1998	Mosca	—	—	—	—
AJ	6,159,073	12/2000	Wiswesser et al.	—	—	—	—
AK	6,413,145	07/2002	Pinson, II et al.	—	—	—	—
AL	6,422,927	07/2002	Zuniga	—	—	—	—

Foreign Patent Documents or Published Foreign Patent Applications

Examiner Initial	Desig. ID	Document Number	Publication Date	Country or Patent Office	Class	Subclass	Translation	
							Yes	No
AM	DE 3801969 A	07/1989	DE	—	—	—	English Abstract	—
AN	EP 0879678 A	11/1998	EPO	—	—	—	—	—
AO	EP 0904895 A	03/1999	EPO	—	—	—	—	—

Other Documents (include Author, Title, Date, and Place of Publication)

Examiner Initial	Desig. ID	Document
AP	Wijekoon et al., "Minimization of Metal Loss during Chemical Mechanical Planerization of Copper-Oxide and Copper – Low κ Damascene Structures", March 2002, Santa Clara, CA, 4 pp.	
AQ	Ravid et al., "Copper CMP Planarity Control Using ITM", 2000, Rehovoth, Israel, 7 pp.	
AR	Pan et al., "Copper CMP and Process Control", Final Paper submitted to CMP-MIC Conference, February 11-12, 1999, Santa Clara, CA and Cambridge, MA, 7 pp.	
AS	Zhang et al., "Automated Process Control of Within-Wafer and Wafer-to-Wafer Uniformity in Oxide CMP", March 2002, Santa Clara, CA, 6 pp.	

Examiner Signature

Date Considered

9/23/05

EXAMINER: Initials citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.